

STARPOWER

SEMICONDUCTOR™

IGBT

GD400SGK120C2S

Molding Type Module

1200V/400A 1 in one-package

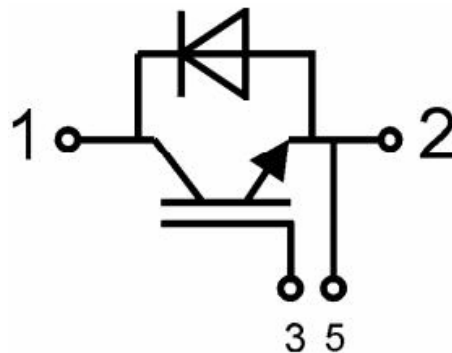
General Description

STARPOWER IGBT Power Module provides ultra low conduction and switching loss as well as short circuit ruggedness. They are designed for the applications such as UPS and SMPS.



Features

- Low $V_{CE(sat)}$ non punch through IGBT technology
- 10 μ s short circuit capability
- $V_{CE(sat)}$ with positive temperature coefficient
- Latch-up free
- Low inductance case
- Fast & soft reverse recovery anti-parallel FWD
- Isolated copper baseplate using DBC technology



Equivalent Circuit Schematic

Typical Applications

- UPS
- Switching mode power supplies
- Electronic welders at f_{sw} up to 25kHz

Absolute Maximum Ratings $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Description	GD400SGK120C2S	Units
V_{CES}	Collector-Emitter Voltage	1200	V

Symbol	Description	GD400SGK120C2S	Units
V_{GES}	Gate-Emitter Voltage	$\pm 20V$	V
I_C	Collector Current @ $T_C=25^\circ C$ @ $T_C=80^\circ C$	550	A
		400	
$I_{CM(1)}$	Pulsed Collector Current $t_p=1ms$	800	A
I_F	Diode Continuous Forward Current	400	A
I_{FM}	Diode Maximum Forward Current	800	A
P_D	Maximum power Dissipation @ $T_j=150^\circ C$	2500	W
T_{SC}	Short Circuit Withstand Time @ $T_j=125^\circ C$	10	μs
T_j	Operating Junction Temperature	-40 to +150	$^\circ C$
T_{STG}	Storage Temperature Range	-40 to +125	$^\circ C$
I^2t -value, Diode	$V_R=0V, t=10ms, T_j=125^\circ C$	27500	A^2s
V_{ISO}	Isolation Voltage RMS, $f=50Hz, t=1min$	2500	V
Mounting Torque	Power Terminal Screw:M4	1.1 to 2.0	N.m
	Power Terminal Screw:M6	2.5 to 5.0	
	Mounting Screw:M6	3.0 to 6.0	N.m

Notes:

(1) Repetitive rating: Pulse width limited by max. junction temperature

Electrical Characteristics of IGBT $T_C=25^\circ C$ unless otherwise noted**Off Characteristics**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{CES}	Collector-Emitter Breakdown Voltage	$T_j=25^\circ C$	1200			V
I_{CES}	Collector Cut-Off Current	$V_{CE}=V_{CES}, V_{GE}=0V,$ $T_j=25^\circ C$			5.0	mA
I_{GES}	Gate-Emitter Leakage Current	$V_{GE}=V_{GES}, V_{CE}=0V,$ $T_j=25^\circ C$			400	nA

On Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=5.0mA, V_{CE}=V_{GE},$ $T_j=25^\circ C$	4.5	5.1	5.5	V
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	$I_C=400A, V_{GE}=15V, T_j=25^\circ C$		2.2		V
		$I_C=400A, V_{GE}=15V,$ $T_j=125^\circ C$		2.5		

Switching Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=600V, I_C=400A,$ $R_G=3.3\Omega, V_{GE} = \pm 15V,$ $T_j=25^\circ C$		258		ns
t_r	Rise Time			110		ns
$t_{d(off)}$	Turn-Off Delay Time			285		ns

t_f	Fall Time	$V_{CC}=600V, I_C=400A,$ $R_G=3.3\Omega, V_{GE} = \pm 15V,$ $T_j= 25^\circ C$	70		ns
E_{on}	Turn-On Switching Loss		45		mJ
E_{off}	Turn-Off Switching Loss		26		mJ
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=600V, I_C=400A,$ $R_G=3.3\Omega, V_{GE} = \pm 15V,$ $T_j= 125^\circ C$	260		ns
t_r	Rise Time		120		ns
$t_{d(off)}$	Turn-Off Delay Time		300		ns
t_f	Fall Time		80		ns
E_{on}	Turn-On Switching Loss		60		mJ
E_{off}	Turn-Off Switching Loss		40		mJ
C_{ies}	Input Capacitance	$V_{CE} = 25V, f=1.0MHz,$ $V_{GE} = 0V$	74.7		nF
C_{oes}	Output Capacitance		3.3		nF
C_{res}	Reverse Transfer Capacitance		0.64		nF
I_{SC}	SC Data	$t_{sc} \leq 10\mu s, V_{GE}=15V,$ $T_j=125^\circ C, V_{CC}=900V,$ $V_{CEM} \leq 1200V$	2400		A
L_{CE}	Stray Inductance		16		nH
$R_{CC'+EE'}$	Module lead resistance, terminal to chip	$T_C=25^\circ C$	0.50		m Ω

Electrical Characteristics of DIODE $T_C=25^\circ C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_F	Diode Forward Voltage	$I_F=400A$	$T_j=25^\circ C$	2.0	2.3	V
			$T_j=125^\circ C$	2.2	2.5	
Q_r	Diode Reverse Recovery Charge	$I_F=400A,$ $V_R=600V,$ $di/dt=-4100A/\mu s,$ $V_{GE}=-15V$	$T_j=25^\circ C$	31		μC
			$T_j=125^\circ C$	66		
I_{RM}	Diode Peak Reverse Recovery Current		$T_j=25^\circ C$	300		A
			$T_j=125^\circ C$	410		
E_{rec}	Reverse Recovery Energy		$T_j=25^\circ C$	12		mJ
			$T_j=125^\circ C$	28		

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case (IGBT Part, per 1/2 Module)		0.05	K/W
$R_{\theta JC}$	Junction-to-Case (DIODE Part, per 1/2 Module)		0.08	K/W
$R_{\theta CS}$	Case-to-Sink (Conductive grease applied)	0.035		K/W
Weight	Weight of Module	340		g

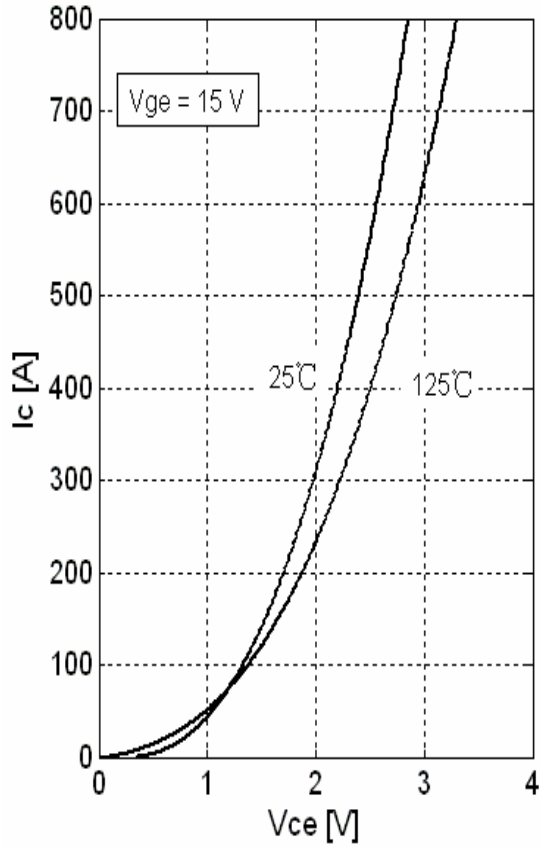


Fig 1. Typical Output Characteristics

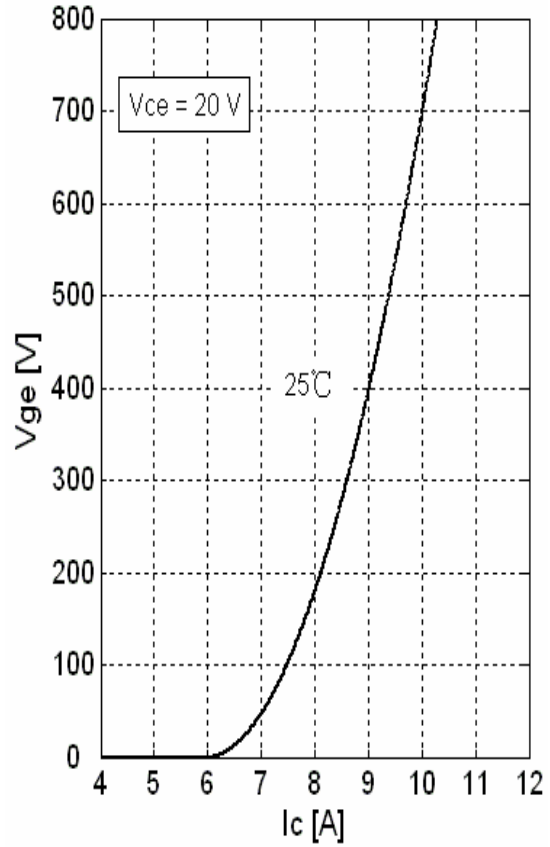


Fig 2. Typical Transfer Characteristics

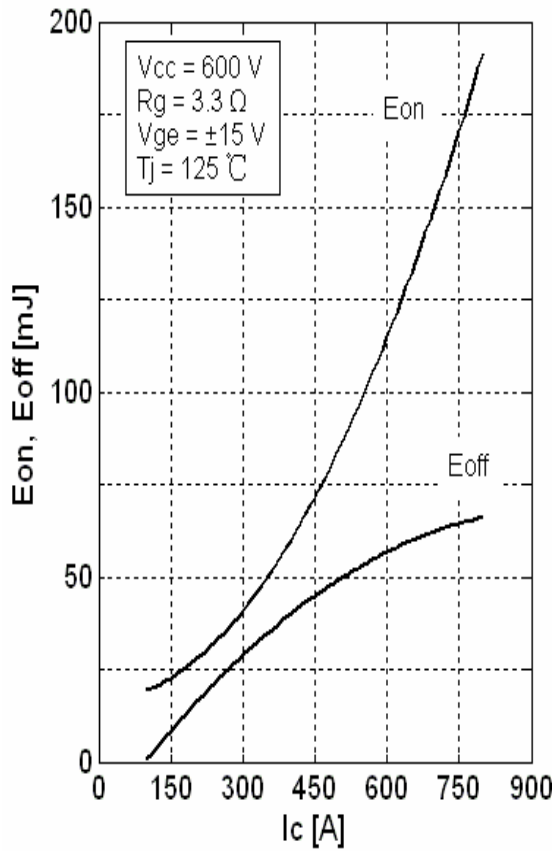


Fig 3. Switching Loss vs Collector Current

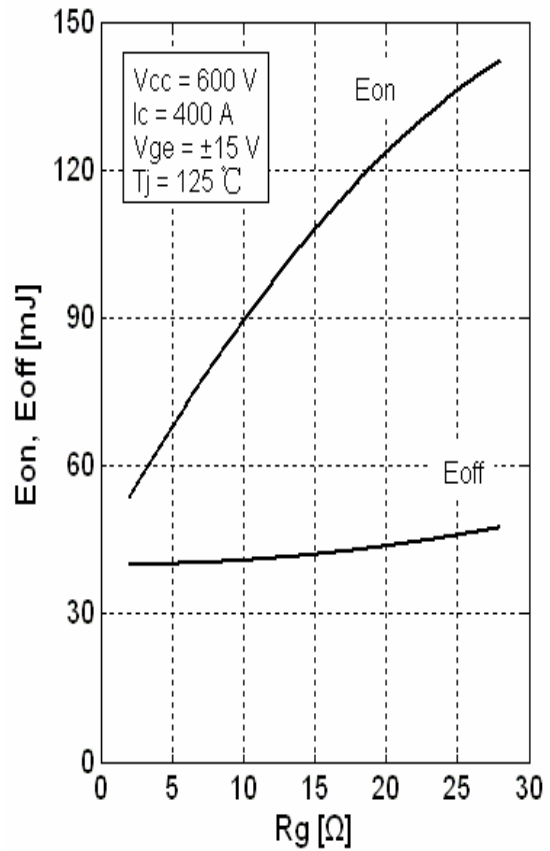


Fig 4. Switching Loss vs Gate Resistor

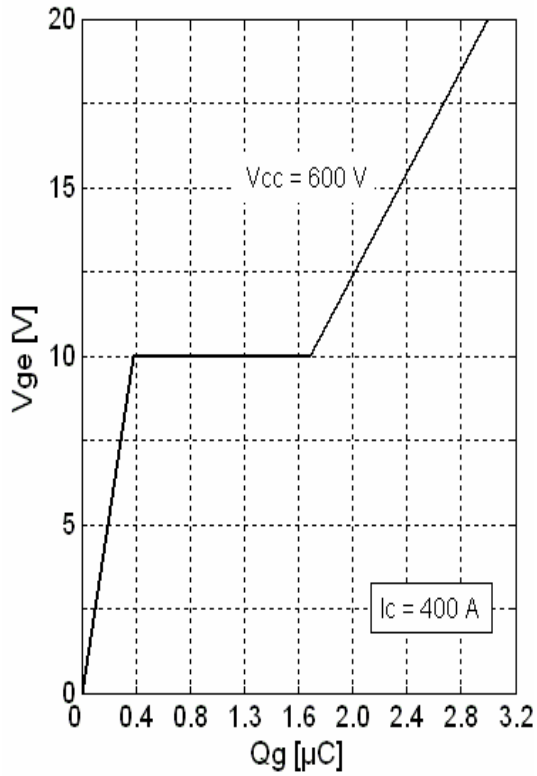


Fig 5. Gate Charge Characteristics

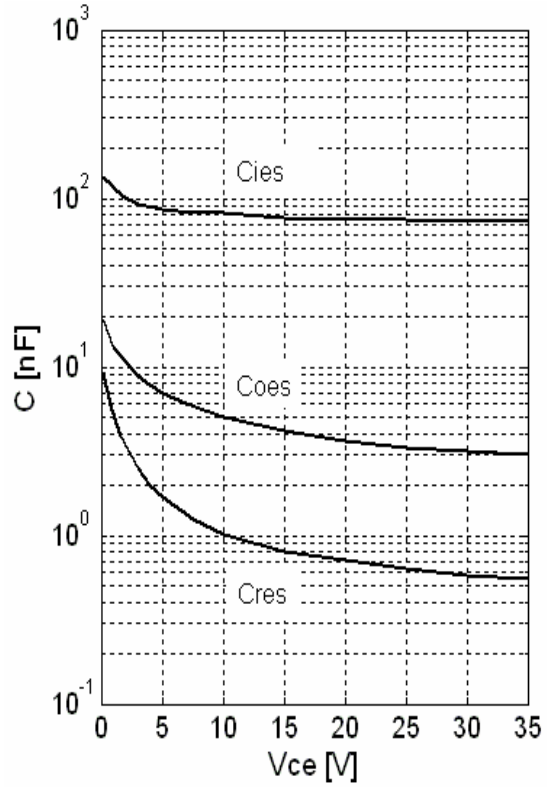


Fig 6. Typical Capacitance vs Collector-Emitter Voltage

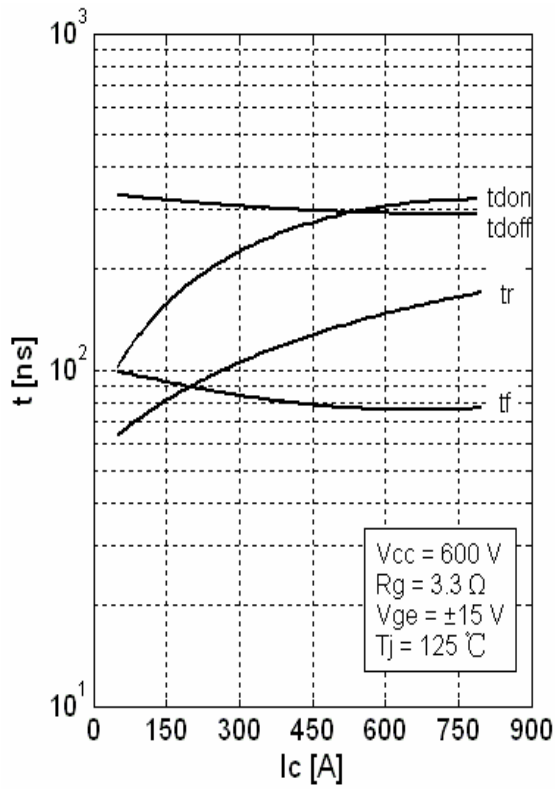


Fig 7. Typical Switching Times vs I_c

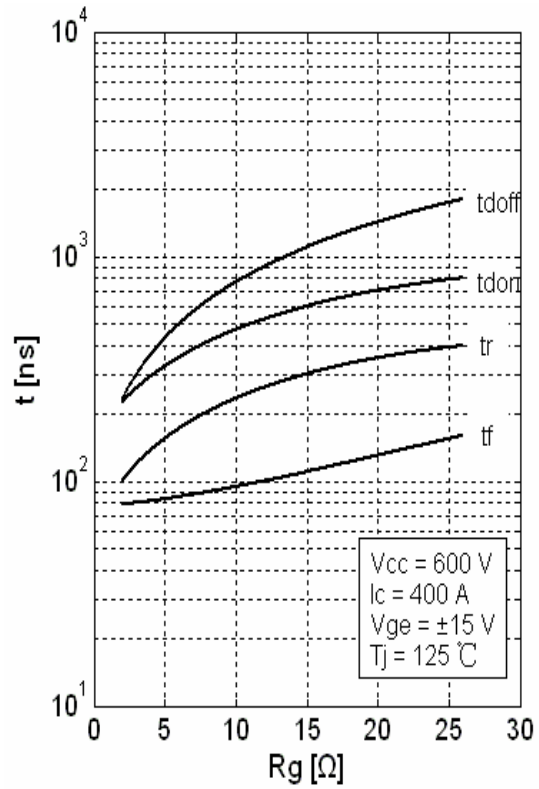


Fig 8. Typical Switching Times vs Gate Resistance R_G

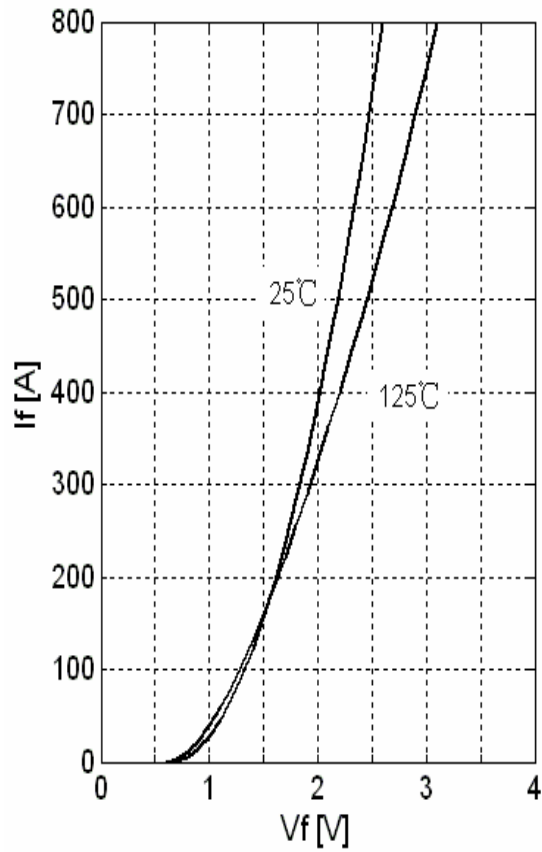


Fig 9. Typical Forward Characteristics (diode)

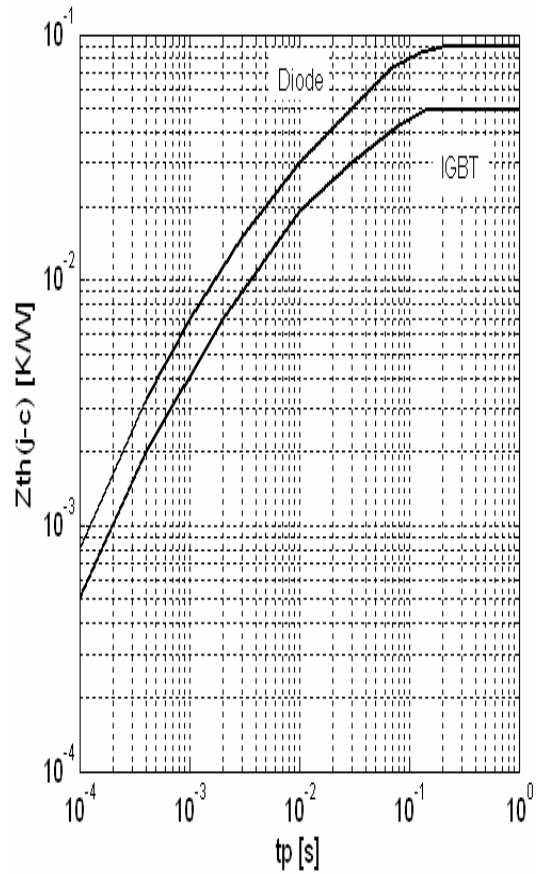
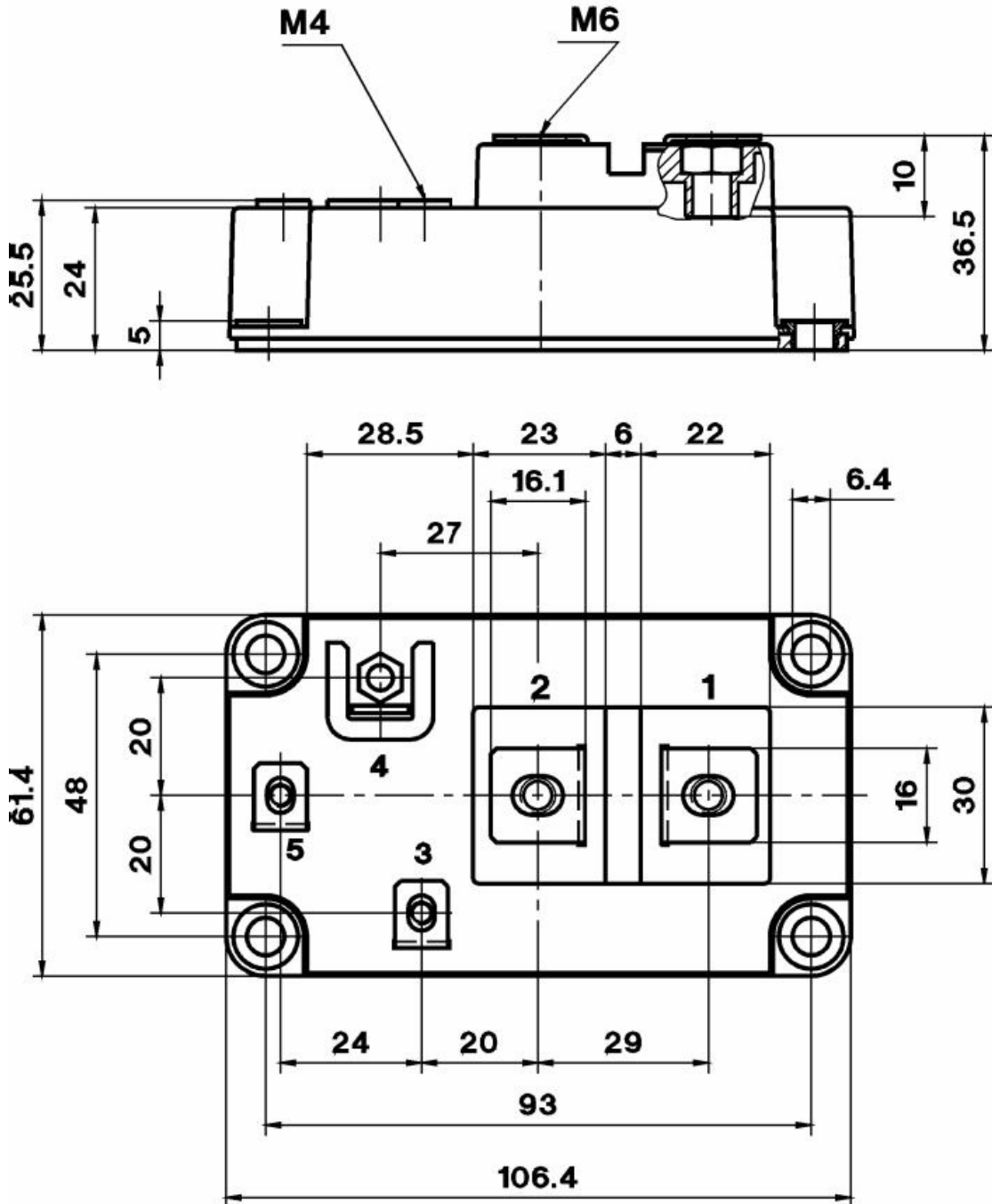


Fig 10. Transient thermal impedance

Package Dimension

Dimensions in Millimeters



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